| [L] | Hits | Search Text | DB | Time stamp |
|--------|----------|--|-----------------------|------------|
| Number | | | UCDATE. | 2003/05/19 |
| 1 | 116541 | gasket polytetrafluorethylene | USPAT; US-PGPUB; | 05:01 |
| | | | EPO; JPO; | |
| | | | DERWENT; |] |
| | | | IBM_TDB | ! |
| 2 | 25 | (gasket polytetrafluorethylene) same | USPAT; | 2003/05/19 |
| - | | lossy | US-PGPUB; | 05:01 |
| | | | EPO; JPO; DERWENT; | 1 |
| ļ | | | IBM TDB | |
|]_ | 2858366 | (semiconductor processor microprocessor | USPAT; | 2003/05/19 |
| 3 | 2030300 | chip die ic (integrated adj circuit)) | US-PGPUB; | 05:03 |
| İ | <u> </u> | | EPO; JPO; | |
| | | | DERWENT; | |
| | | | IBM_TDB USPAT; | 2003/05/19 |
| 4 | 430180 | | US-PGPUB; | 05:04 |
| | | element metal) | EPO; JPO; | |
| | | | DERWENT; | 1 |
| | | | IBM_TDB | |
| 5 | 420607 | eds electrostatic electro-static (electro | USPAT; | 2003/05/19 |
| | | adj3 static) | US-PGPUB; | 05:05 |
| | | | EPO; JPO; DERWENT; | |
| | | | IBM TDB | |
| | 26672 | (eds electrostatic electro-static | USPAT; | 2003/05/19 |
| 6 | 20072 | (electro adj3 static)) with (discharge | US-PGPUB; | 05:05 |
| | | discharging) | EPO; JPO; | 1 |
| | | | DERWENT; | |
| 1 | | s and sand | IBM_TDB USPAT; | 2003/05/19 |
| 7 | 503 | (gasket polytetrafluorethylene) and ((semiconductor processor microprocessor | US-PGPUB; | 05:05 |
| | | chip die ic (integrated adj circuit))) | EPO; JPO; | |
| | | and (heat with (dissipate sink spreader | DERWENT; | |
| | | slug element metal)) and (eds | IBM_TDB | |
| Ì | | electrostatic electro-static (electro | | |
| | | adj3 static)) | USPAT; | 2003/05/19 |
| 8 | 44 | (gasket polytetrafluorethylene) and ((semiconductor processor microprocessor | US-PGPUB; | 05:24 |
| | | chip die ic (integrated adj circuit))) | EPO; JPO; | |
| | | and (heat with (dissipate sink spreader | DERWENT; | |
| | | slug element metal)) and ((eds | IBM_TDB | İ |
| | | electrostatic electro-static (electro | | |
| | | adj3 static)) with (discharge | | |
| | 459 | discharging)) ((gasket polytetrafluorethylene) and | USPAT; | 2003/05/19 |
| 9 | 459 | ((semiconductor processor microprocessor | US-PGPUB; | 05:24 |
| | | chip die ic (integrated adj circuit))) | EPO; JPO; | |
| | | and (heat with (dissipate sink spreader | DERWENT; | |
| | | slug element metal)) and (eds | IBM_TDB | |
| | | electrostatic electro-static (electro | | |
| | | adj3 static))) not ((gasket polytetrafluorethylene) and | | |
| | 1 | ((semiconductor processor microprocessor | | |
| | 1 | chip die ic (integrated adj circuit))) | | |
| | | and (heat with (dissipate sink spreader | | |
| | 1 | slug element metal)) and ((eds | | |
| | | electrostatic electro-static (electro | | |
| | | adj3 static)) with (discharge discharging))) | 1 | ļ |
| | | urachardina) / / | <u> </u> | |

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| 10 | (((gasket polytetrafluorethylene) a | cessor US-PGPUB; U5:24 t))) EPO; JPO; DERWENT; IBM_TDB tro cessor t))) eader | |
|--------|---|--|--|
| l i | electrostatic electro-static (electrostatic)) with (discharge discharging)))) and package | etro | |